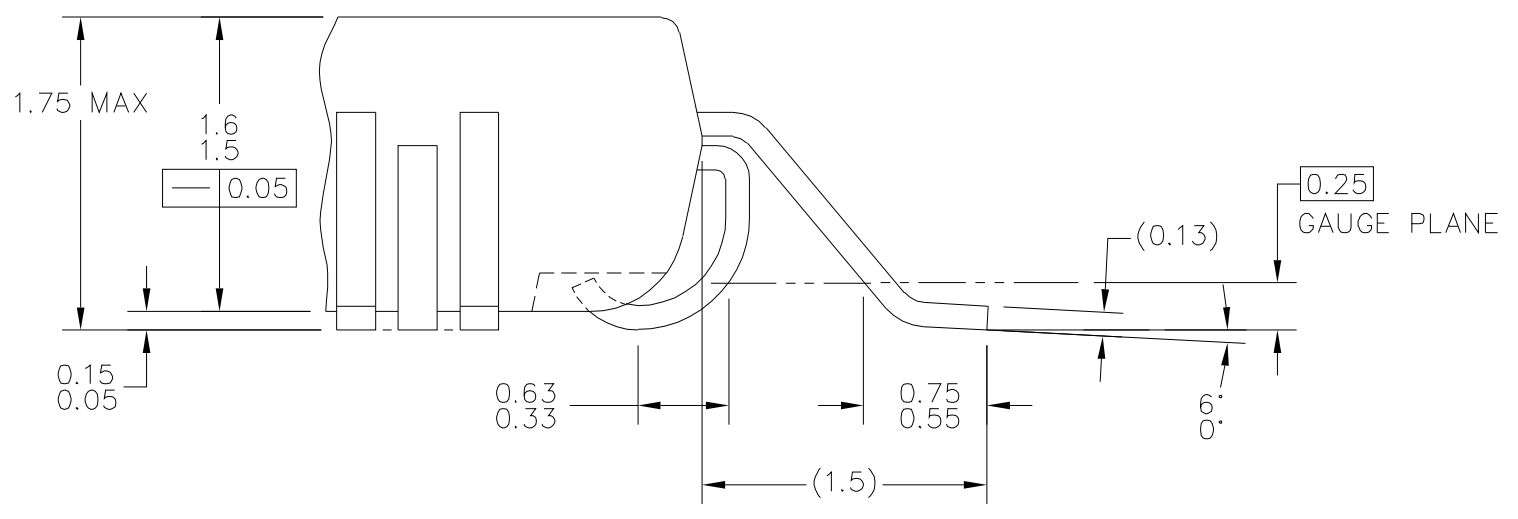


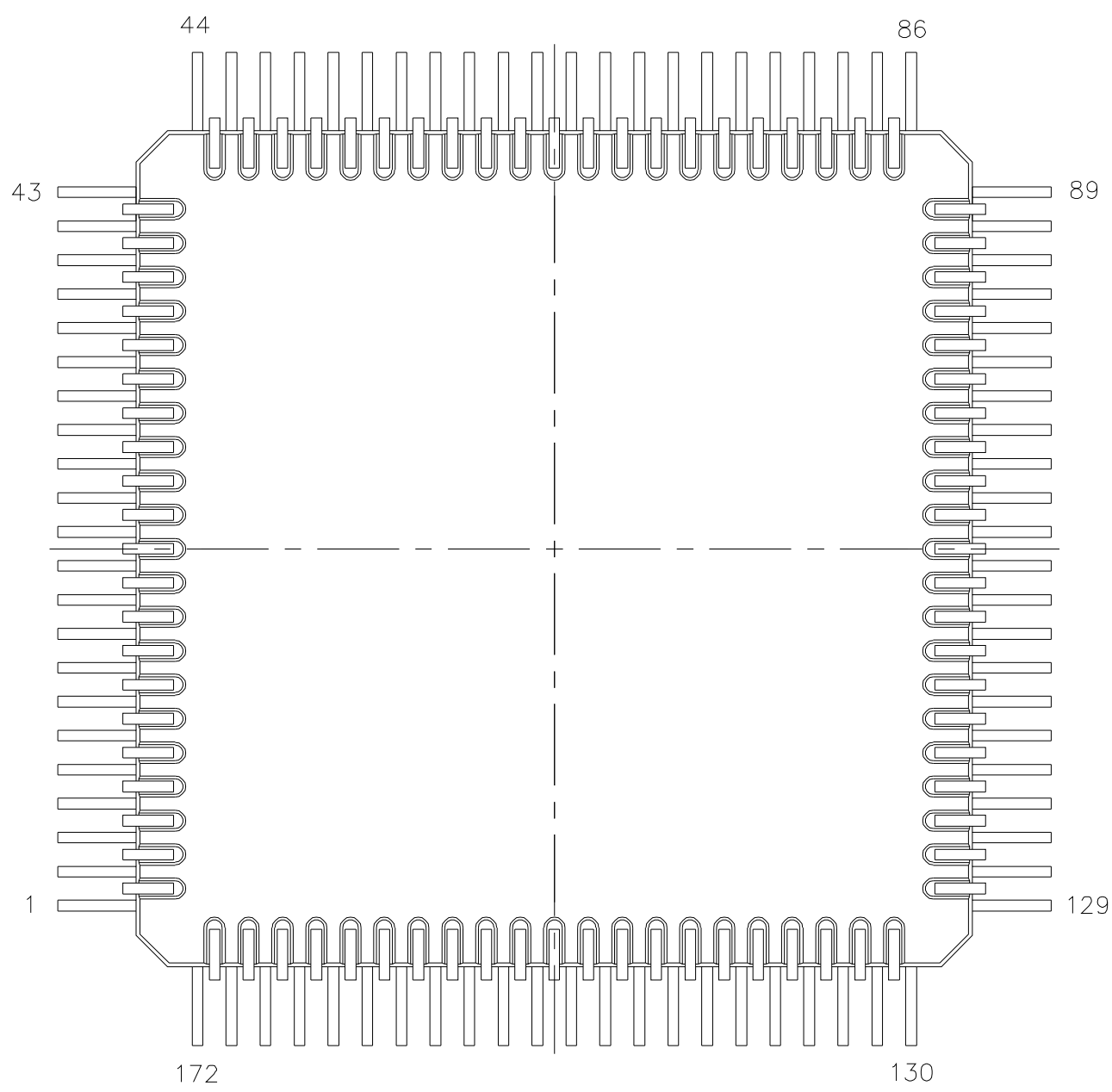
DETAIL E



DETAIL F



MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01107D	REVISION: X2	PAGE: 2
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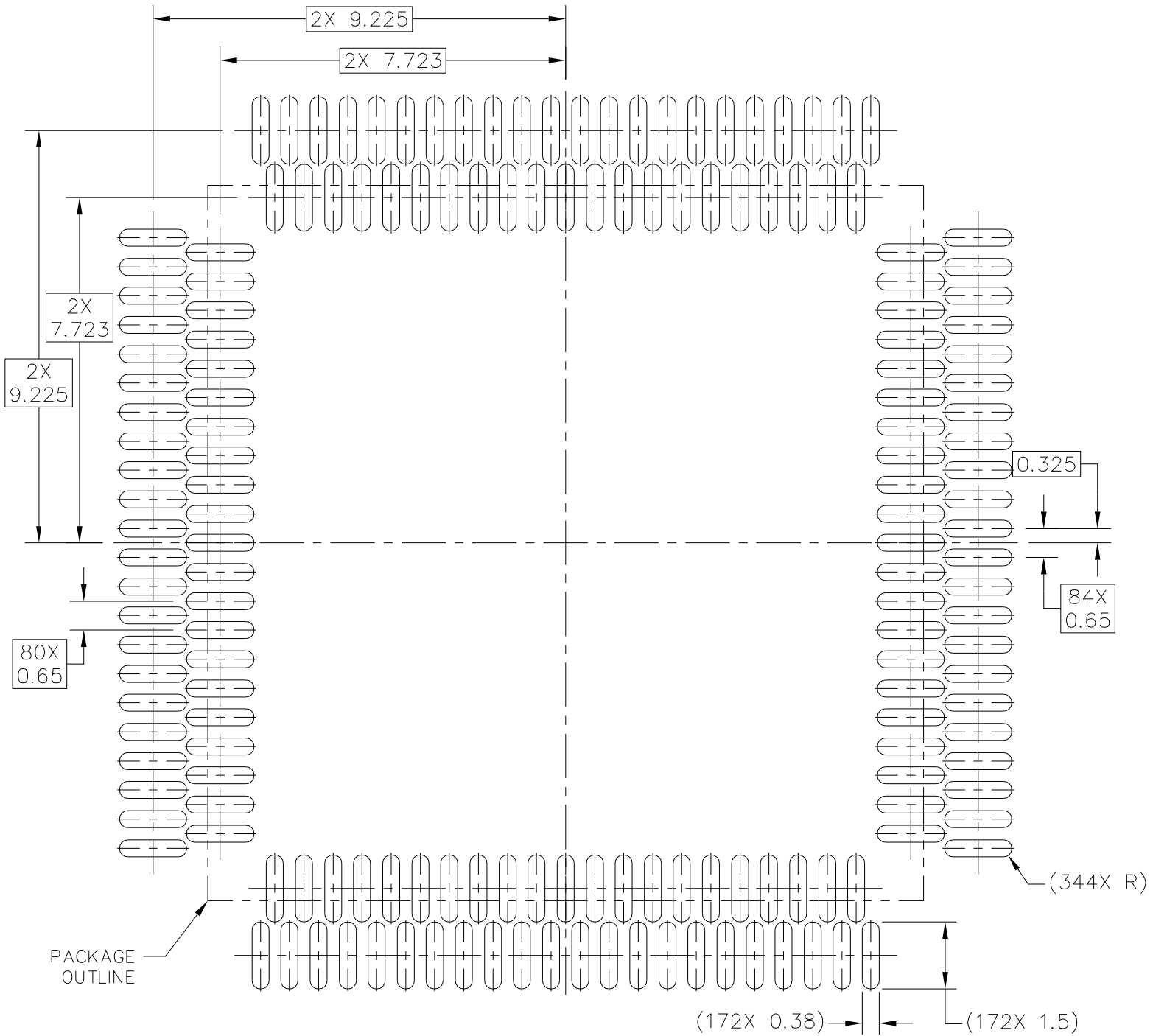
VIEW G-G



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DATE: 19 AUG 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01107D	REVISION: X2	PAGE: 3
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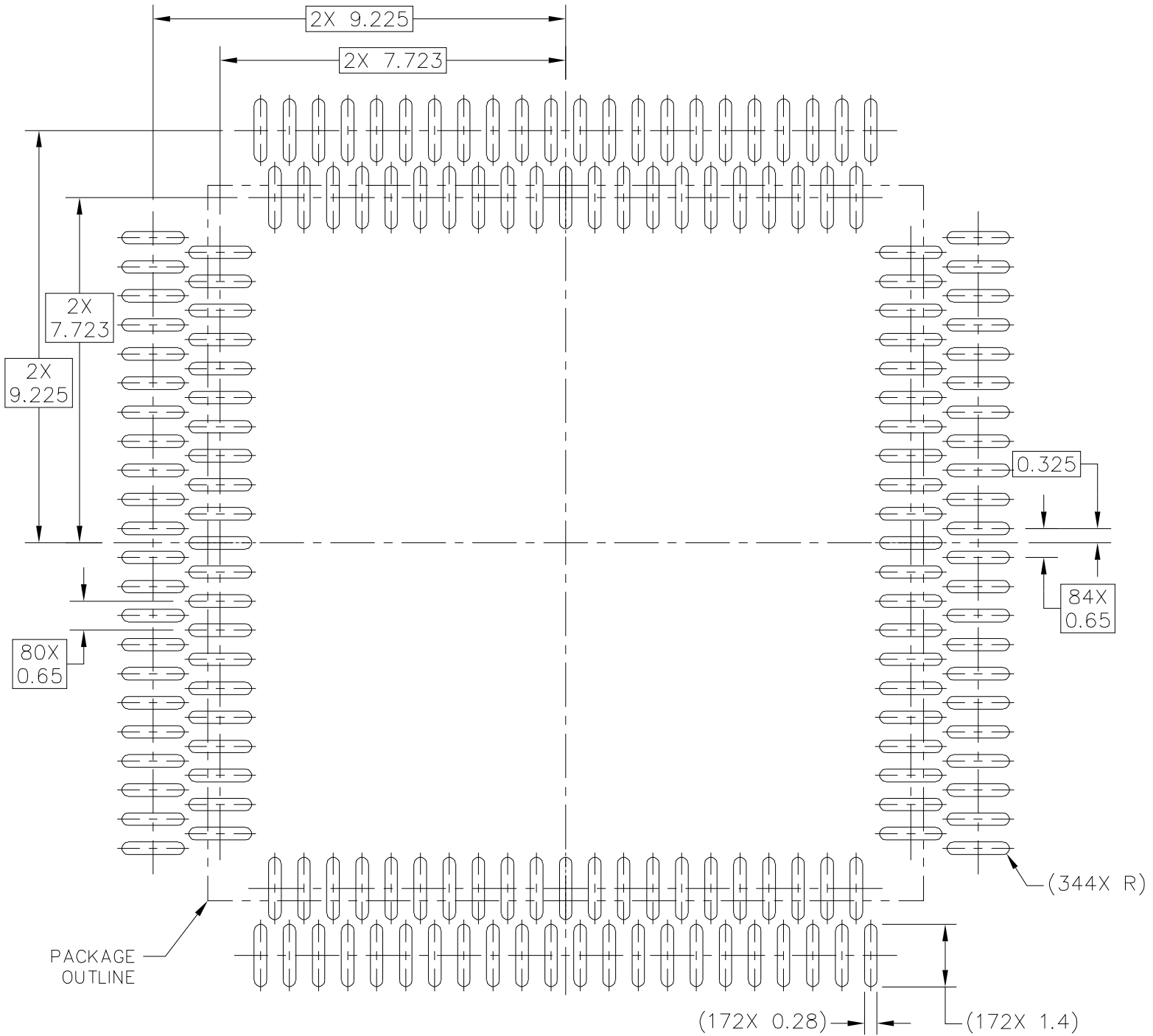


PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.



MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01107D	REVISION: X2	PAGE: 4
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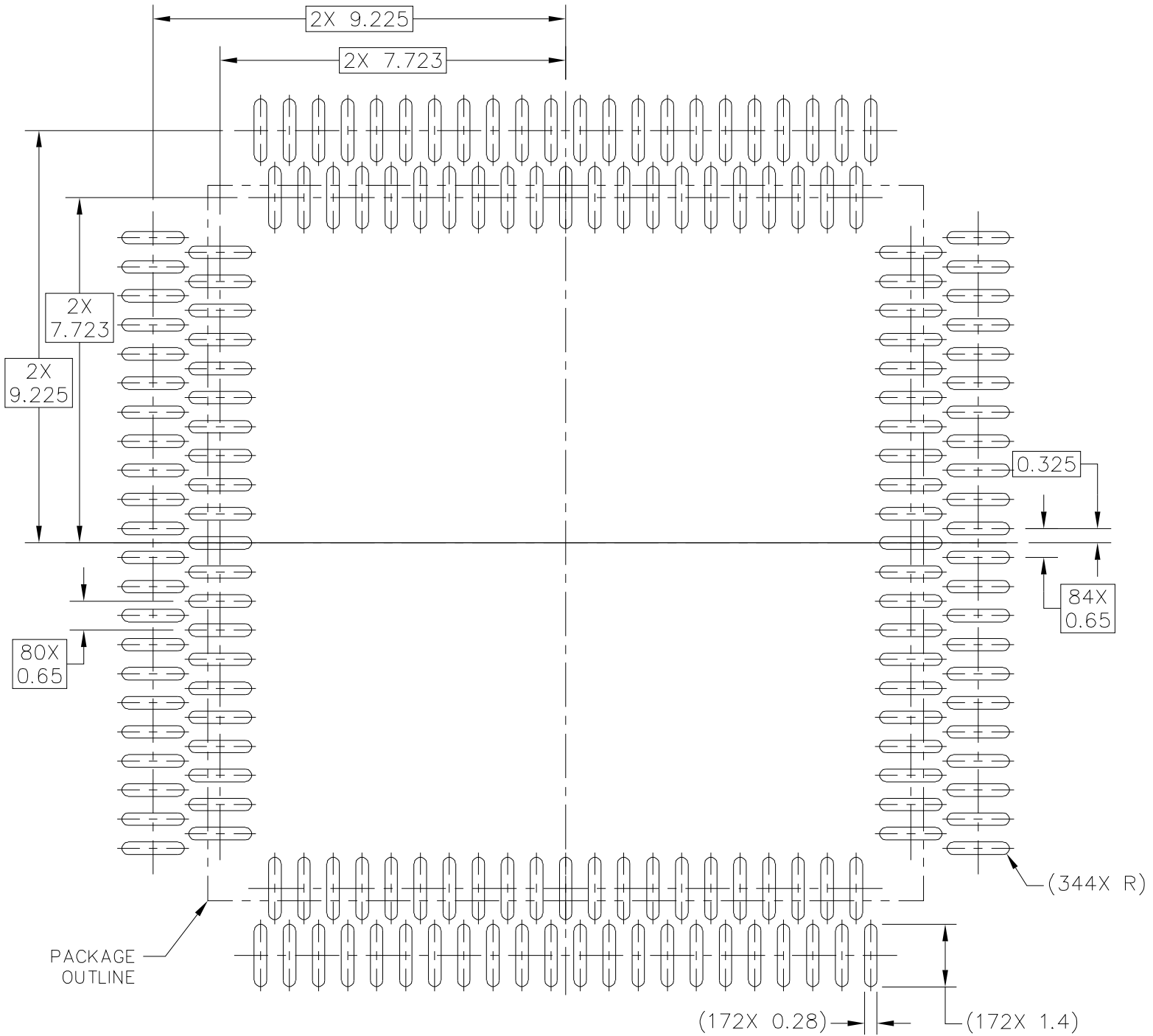


PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.



MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01107D	REVISION: X2	PAGE: 5
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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.



MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01107D	REVISION: X2	PAGE: 6
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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.

6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.

7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.

8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.



MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01107D	REVISION: X2	PAGE: 7
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REV	ORIGINATOR	REVISION DETAILS	DRAFTER	DATE
X0	XS PANG	RELEASED FOR ENGINEERING EVALUATION (DAR #27042)	GIDEON	23 AUG 2017
X1	MARIANO CHING	CHANGED BASE LEAD WIDTH TO 0.23/0.17 AND LEAD WIDTH TO 0.27/0.17. UPDATED BOTTOM MOLD CORNERS TO REFLECT RADIUS OF 0.5. (DAR #28107)	GIDEON	11 JAN 2019
X2	XS PANG	BENCHMARKED MAXQFP 10X10 CASE OUTLINE 98ASA01570D_X0 FORMAT AND DIMENSIONING METHOD. (DAR #30329)	YM LEE	19 AUG 2020



MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01107D	REVISION: X2	PAGE: 8
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